SB10T100

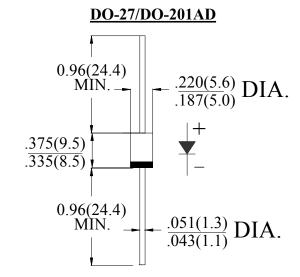
10.0AMPS. SCHOTTKY BARRIER RECTIFIERS

FEATURE

- . For surface mounted application
- . High current capability
- . Low forward voltage drop
- . Low power loss, high efficiency
- . High surge current capability
- . High temperature soldering guaranteed: 260°C /10sec/ 0.375" lead length at 5 lbs tension

MECHANICAL DATA

- . Terminal: Solder plated
- Case: Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy (free halogen)
- . Polarity: color band denotes cathode
- . Mounting position: any



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

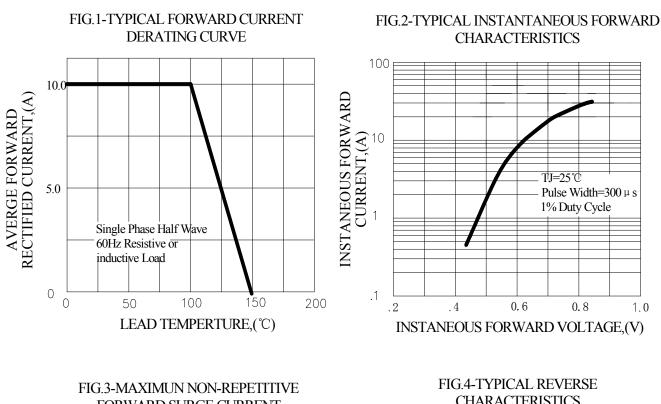
For capacitive load, derate current by 20%

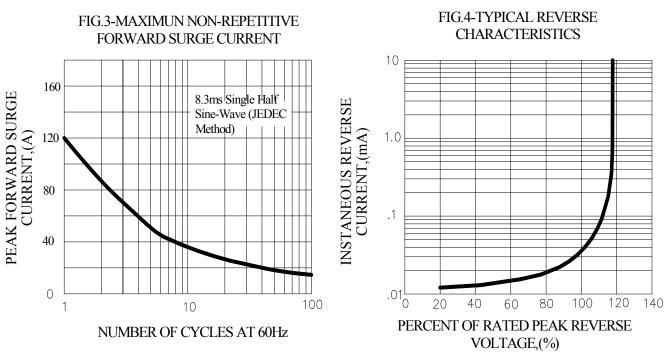
Type Number	SYM BOL	SB10T100	units
Maximum Recurrent Peak Reverse Voltage	<i>V</i> _{RRM} 100		V
Maximum RMS Voltage	$V_{ m RMS}$	70	V
Maximum DC blocking Voltage	$V_{ m DC}$	100	V
Maximum Average Forward Rectified Current	$I_{\mathrm{F(AV)}}$	10.0	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	$I_{ m FSM}$	120	A
Maximum Forward Voltage at 10.0A DC	$V_{\rm F(MAX)}$	0.7	V
Maximum DC Reverse Current @T;=25°C at rated DC blocking voltage @T;=100°C	$I_{ m R}$	0.1	mA
Typical Junction Capacitance (Note1)	$C_{ m J}$	800	pF
Typical Thermal Resistance (Note2)	$R_{(\mathrm{JL})}$	12	°C/W
Storage Temperature	$T_{ m STG}$	-55 to +150	°C
Operating Junction Temperature	$T_{ m J}$	-55 to +150	°C

Note:

- 1. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
- 2. Thermal Resistance from Junction to Ambient at 0.375"(9.5mm)lead length, vertical P.C.Board Mounted

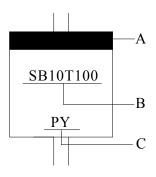
RATING AND CHARACTERISTIC CURVES (SB10T100)





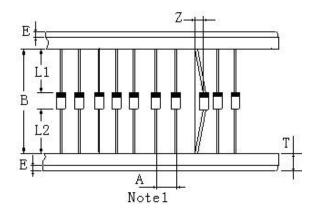
Marking and packaging illustration

1. Marking



SYMBOL	Explanation	
A	Color Band Denotes Cathode	
В	Product Name	
C	Trademark	

2. Packaging



TOTAL	SYMBOL	SPECIFICATIONS	SPECIFICATIONS
ITEM		(mm)	(inch)
Component alignment	Z	1.2max	0.048max
Tape width	T	6.0 ± 0.4	0.236 ± 0.016
Exposed adhesive	Е	0.8max	0.032max
Body eccentricity	L1-L2	1.0max	0.040max
Component	A	10.0 ± 0.5	0.4 ± 0.02
Inner tap	В	52.0~53.5	2.05~2.11

NOTE:

Each component lead shall be sandwiched between tapes for a minimum of 2.5mm (0.1inch)